

## C0805X331G2TACTU

Aliases (C0805X331G2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 330 pF, 2%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0805, 0.6 mm



Click [here](#) for the 3D model.

### General Information

Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

### Dimensions

Chip Size	0805
L	2mm +/-0.3mm
W	1.25mm +/-0.3mm
T	0.78mm +/-0.20mm
S	0.6mm MIN
B	0.5mm +/-0.25mm

### Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

### Specifications

Capacitance	330 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	2%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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